



SCCS064B - August 1994 - Revised September 2001

CY74FCT16827T CY74FCT162827T

20-Bit Buffers/Line Drivers

Features

- I_{off} Supports Partial-Power-Down Mode Operation
- Edge-rate control circuitry for significantly improved noise characteristics
- Typical output skew < 250 ps
- ESD > 2000V
- TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages
- Industrial temperature range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 5\text{V} \pm 10\%$

CY74FCT16827T Features:

- 64 mA sink current, 32 mA source current
- Typical V_{OLP} (ground bounce) < 1.0V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

CY74FCT162827T Features:

- Balanced 24 mA output drivers
- Reduced system switching noise
- Typical V_{OLP} (ground bounce) < 0.6V at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$

Functional Description

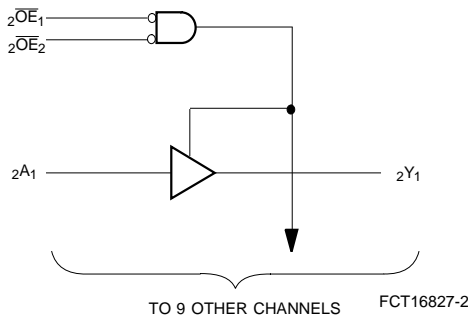
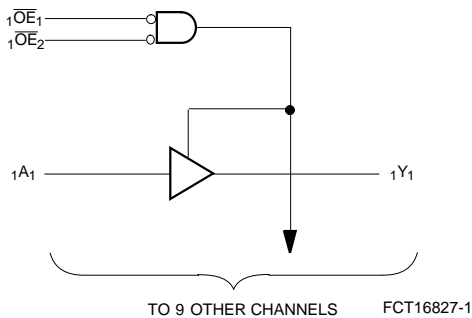
The CY74FCT16827T 20-bit buffer/line driver and the CY74FCT162827T 20-bit buffer/line driver provide high-performance bus interface buffering for wide data/address paths or buses carrying parity. These parts can be used as a single 20-bit buffer or two 10-bit buffers. Each 10-bit buffer has a pair of NANDed OE for increased flexibility.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

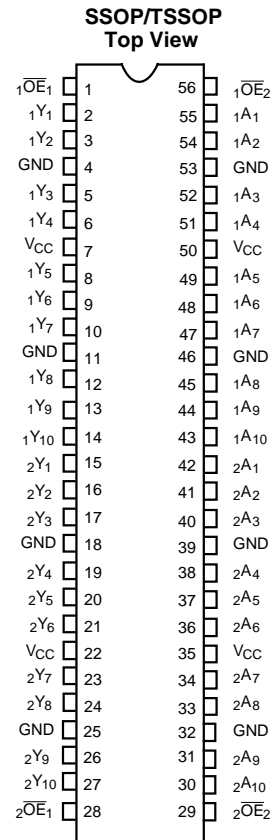
The CY74FCT16827T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162827T has 24-mA balanced output drivers with current-limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal undershoot and reduced ground bounce. The CY74FCT162827T is ideal for driving transmission lines.

Logic Block Diagrams



Pin Configuration



FCT16827-3

Pin Description

| Name | Description |
|-----------------|-----------------------------------|
| \overline{OE} | Output Enable Inputs (Active LOW) |
| A | Data Inputs |
| Y | Three-State Outputs |

Function Table^[1]

| Inputs | | | Outputs |
|-------------------|-------------------|---|---------|
| \overline{OE}_1 | \overline{OE}_2 | A | Y |
| L | L | L | L |
| L | L | H | H |
| H | X | X | Z |
| X | H | X | Z |

Maximum Ratings^[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -55°C to $+125^{\circ}\text{C}$

Ambient Temperature with Power Applied -55°C to $+125^{\circ}\text{C}$

DC Input Voltage -0.5V to $+7.0\text{V}$

DC Output Voltage -0.5V to $+7.0\text{V}$

DC Output Current (Maximum Sink Current/Pin) -60 to $+120\text{ mA}$

Power Dissipation 1.0W

Static Discharge Voltage $>2001\text{V}$ (per MIL-STD-883, Method 3015)

Operating Range

| Range | Ambient Temperature | V_{CC} |
|------------|--|----------------------|
| Industrial | -40°C to $+85^{\circ}\text{C}$ | $5\text{V} \pm 10\%$ |

Electrical Characteristics Over the Operating Range

| Parameter | Description | Test Conditions | Min. | Typ. ^[4] | Max. | Unit |
|-----------|---|---|------|---------------------|---------|---------------|
| V_{IH} | Input HIGH Voltage | | 2.0 | | | V |
| V_{IL} | Input LOW Voltage | | | | 0.8 | V |
| V_H | Input Hysteresis ^[5] | | | 100 | | mV |
| V_{IK} | Input Clamp Diode Voltage | $V_{CC}=\text{Min.}, I_{IN}=-18\text{ mA}$ | | -0.7 | -1.2 | V |
| I_{IH} | Input HIGH Current | $V_{CC}=\text{Max.}, V_I=V_{CC}$ | | | ± 1 | μA |
| I_{IL} | Input LOW Current | $V_{CC}=\text{Max.}, V_I=\text{GND}$ | | | ± 1 | μA |
| I_{OZH} | High Impedance Output Current (Three-State Output pins) | $V_{CC}=\text{Max.}, V_{OUT}=2.7\text{V}$ | | | ± 1 | μA |
| I_{OZL} | High Impedance Output Current (Three-State Output pins) | $V_{CC}=\text{Max.}, V_{OUT}=0.5\text{V}$ | | | ± 1 | μA |
| I_{OS} | Short Circuit Current ^[6] | $V_{CC}=\text{Max.}, V_{OUT}=\text{GND}$ | -80 | -140 | -200 | mA |
| I_O | Output Drive Current ^[6] | $V_{CC}=\text{Max.}, V_{OUT}=2.5\text{V}$ | -50 | | -180 | mA |
| I_{OFF} | Power-Off Disable | $V_{CC}=0\text{V}, V_{OUT}\leq 4.5\text{V}^{[7]}$ | | | ± 1 | μA |

Output Drive Characteristics for CY74FCT16827T

| Parameter | Description | Test Conditions | Min. | Typ. ^[4] | Max. | Unit |
|-----------|---------------------|--|------|---------------------|------|------|
| V_{OH} | Output HIGH Voltage | $V_{CC}=\text{Min.}, I_{OH}=-3\text{ mA}$ | 2.5 | 3.5 | | V |
| | | $V_{CC}=\text{Min.}, I_{OH}=-15\text{ mA}$ | 2.4 | 3.5 | | |
| | | $V_{CC}=\text{Min.}, I_{OH}=-32\text{ mA}$ | 2.0 | 3.0 | | |
| V_{OL} | Output LOW Voltage | $V_{CC}=\text{Min.}, I_{OL}=64\text{ mA}$ | | 0.2 | 0.55 | V |

- H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = HIGH Impedance.
- Operation beyond the limits set forth may impair the useful life of the device. Unless noted, these limits are over the operating free-air temperature range.
- Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
- Typical values are at $V_{CC}=5.0\text{V}$, $T_A=+25^{\circ}\text{C}$ ambient.
- This parameter is specified but not tested.
- Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.
- Tested at $+25^{\circ}\text{C}$.

Output Drive Characteristics for CY74FCT162827T

| Parameter | Description | Test Conditions | Min. | Typ. ^[4] | Max. | Unit |
|------------------|------------------------------------|---|------|---------------------|------|------|
| I _{ODL} | Output LOW Current ^[6] | V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V | 60 | 115 | 150 | mA |
| I _{ODH} | Output HIGH Current ^[6] | V _{CC} =5V, V _{IN} =V _{IH} or V _{IL} , V _{OUT} =1.5V | -60 | -115 | -150 | mA |
| V _{OH} | Output HIGH Voltage | V _{CC} =Min., I _{OH} =-24 mA | 2.4 | 3.3 | | V |
| V _{OL} | Output LOW Voltage | V _{CC} =Min., I _{OL} =24 mA | | 0.3 | 0.55 | V |

Capacitance^[5] (T_A = +25°C, f = 1.0 MHz)

| Parameter | Description | Test Conditions | Typ. ^[4] | Max. | Unit |
|------------------|--------------------|-----------------------|---------------------|------|------|
| C _{IN} | Input Capacitance | V _{IN} = 0V | 4.5 | 6.0 | pF |
| C _{OUT} | Output Capacitance | V _{OUT} = 0V | 5.5 | 8.0 | pF |

Power Supply Characteristics

| Parameter | Description | Test Conditions | Min. | Typ. ^[4] | Max. | Unit | |
|------------------|--|--|---|---------------------|------|----------------------|----|
| I _{CC} | Quiescent Power Supply Current | V _{CC} =Max. V _{IN} ≤0.2V, V _{IN} ≥V _{CC} -0.2V | — | 5 | 500 | μA | |
| ΔI _{CC} | Quiescent Power Supply Current (TTL inputs HIGH) | V _{CC} =Max. V _{IN} =3.4V ^[8] | — | 0.5 | 1.5 | mA | |
| I _{CCD} | Dynamic Power Supply Current ^[9] | V _{CC} =Max., One Input Toggling, 50% Duty Cycle, Outputs Open, OE ₁ =OE ₂ =GND, | — | 60 | 100 | μA/MHz | |
| I _C | Total Power Supply Current ^[10] | V _{CC} =Max., f ₁ =10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling, OE ₁ =OE ₂ =GND | V _{IN} =V _{CC} or V _{IN} =GND | — | 0.6 | 1.5 | mA |
| | | V _{IN} =3.4V or V _{IN} =GND | — | 0.9 | 2.3 | | |
| | | V _{CC} =Max., f ₁ =2.5 MHz, 50% Duty Cycle, Outputs Open, Twenty Bits Toggling, OE ₁ =OE ₂ =GND | V _{IN} =V _{CC} or V _{IN} =GND | — | 3.0 | 5.5 ^[11] | |
| | | | V _{IN} =3.4V or V _{IN} =GND | — | 8.0 | 20.5 ^[11] | |

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}
I_C = I_{CC} + ΔI_{CC}D_HN_T + I_{CCD}(f₀/2 + f₁N₁)
I_{CC} = Quiescent Current with CMOS input levels
ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
D_H = Duty Cycle for TTL inputs HIGH
N_T = Number of TTL inputs at D_H
I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
f₀ = Clock frequency for registered devices, otherwise zero
f₁ = Input signal frequency
N₁ = Number of inputs changing at f₁
All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range^[12]

| Parameter | Description | Condition ^[13] | CY74FCT16827AT CY74FCT162827AT | | CY74FCT162827BT | | Unit | Fig. No. ^[13] |
|--------------------------------------|--------------------------------|--|-----------------------------------|------|-----------------|------|------|--------------------------|
| | | | Min. | Max. | Min. | Max. | | |
| t _{PLH} t _{PHL} | Propagation Delay A to Y | C _L =50 pF R _L =500Ω | 1.5 | 8.0 | 1.5 | 5.0 | ns | 1, 3 |
| | | C _L =300 pF R _L =500Ω | 1.5 | 15.0 | 1.5 | 13.0 | | |
| t _{PZH} t _{PZL} | Output Enable Time OE to Y | C _L =50 pF R _L =500Ω | 1.5 | 12.0 | 1.5 | 8.0 | ns | 1, 7, 8 |
| | | C _L =300 pF R _L =500Ω | 1.5 | 23.0 | 1.5 | 15.0 | | |
| t _{PHZ} t _{PLZ} | Output Disable Time OE to Y | C _L =5 pF R _L =500Ω | 1.5 | 9.0 | 1.5 | 6.0 | ns | 1, 7, 8 |
| | | C _L =50 pF R _L =500Ω | 1.5 | 10.0 | 1.5 | 7.0 | | |
| t _{SK(O)} | Output Skew ^[14] | | — | 0.5 | — | 0.5 | ns | — |

| Parameter | Description | Condition ^[12] | CY74FCT16827CT CY74FCT162827CT | | Unit | Fig. No. ^[13] |
|--------------------------------------|--------------------------------|--|-----------------------------------|------|------|--------------------------|
| | | | Min. | Max. | | |
| t _{PLH} t _{PHL} | Propagation Delay A to Y | C _L =50 pF R _L =500Ω | 1.5 | 4.2 | ns | 1, 3 |
| | | C _L =300 pF R _L =500Ω | 1.5 | 10.0 | | |
| t _{PZH} t _{PZL} | Output Enable Time OE to Y | C _L =50 pF R _L =500Ω | 1.5 | 5.6 | ns | 1, 7, 8 |
| | | C _L =300 pF R _L =500Ω | 1.5 | 14.0 | | |
| t _{PHZ} t _{PLZ} | Output Disable Time OE to Y | C _L =5 pF R _L =500Ω | 1.5 | 5.7 | ns | 1, 7, 8 |
| | | C _L =50 pF R _L =500Ω | 1.5 | 6.0 | | |
| t _{SK(O)} | Output Skew ^[14] | | — | 0.5 | ns | — |

Notes:

12. Minimum limits are specified but not tested on Propagation Delays.
13. See "Parameter Measurement Information" in the General Information section.
14. Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

Ordering Information CY74FCT16827

| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|------------|------------------------|--------------|-------------------------|-----------------|
| 4.2 | CY74FCT16827CTPACT | Z56 | 56-Lead (240-Mil) TSSOP | Industrial |
| | CY74FCT16827CTPVC/PVCT | O56 | 56-Lead (300-Mil) SSOP | |
| 8.0 | CY74FCT16827ATPVC/PVCT | Z56 | 56-Lead (240-Mil) SSOP | Industrial |

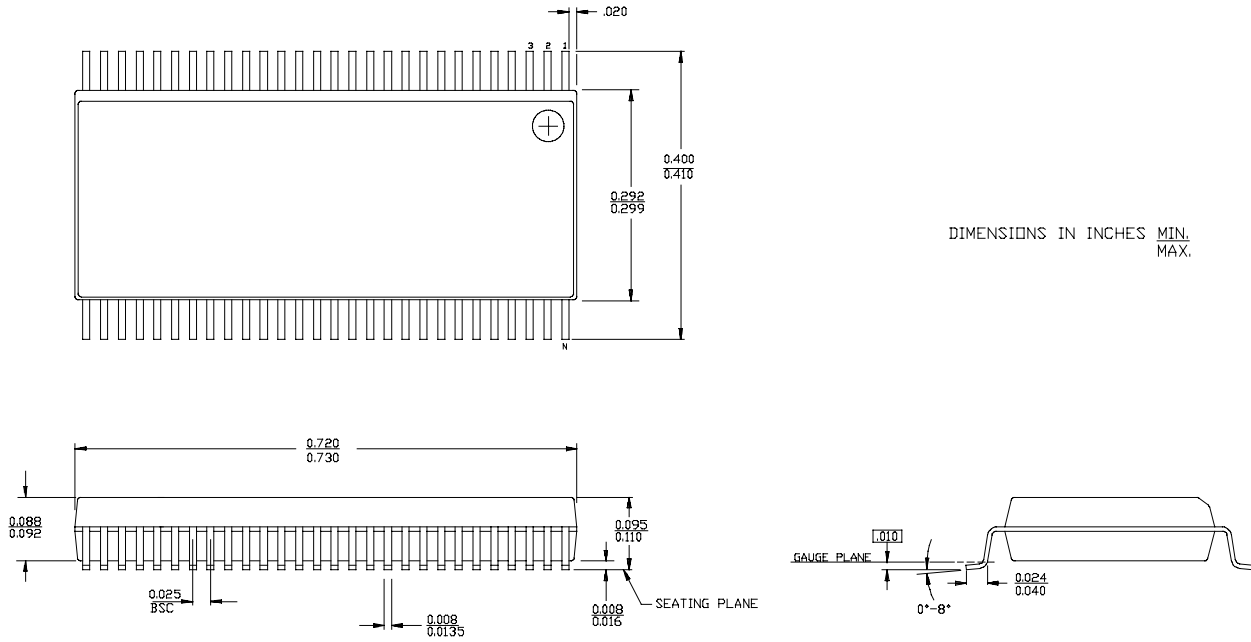
Document #: 38-00393-C

Ordering Information CY74FCT162827

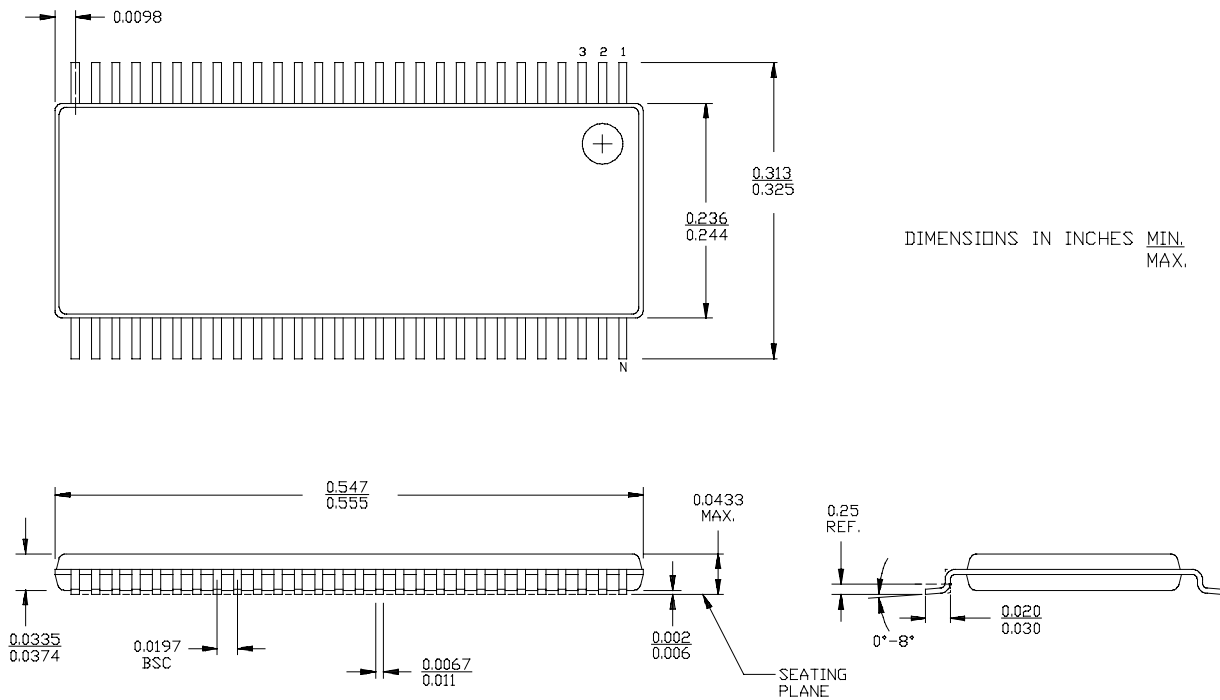
| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|------------|--------------------|--------------|-------------------------|-----------------|
| 4.2 | 74FCT162827CTPACT | Z56 | 56-Lead (240-Mil) TSSOP | Industrial |
| | CY74FCT162827CTPVC | Z56 | 56-Lead (240-Mil) SSOP | |
| | 74FCT162827CTPVCT | Z56 | 56-Lead (240-Mil) SSOP | |
| 5.0 | CY74FCT162827BTPVC | O56 | 56-Lead (300-Mil) SSOP | Industrial |
| | 74FCT162827BTPVCT | O56 | 56-Lead (300-Mil) SSOP | |
| 8.0 | CY74FCT162827ATPVC | O56 | 56-Lead (300-Mil) SSOP | Industrial |
| | 74FCT162827ATPVCT | O56 | 56-Lead (300-Mil) SSOP | |

Package Diagrams

56-Lead Shrunken Small Outline Package O56



56-Lead Thin Shrunken Small Outline Package Z56



PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|--------------------|---------------|--------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| 74FCT162827ATPACT | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827A | Samples |
| 74FCT162827ATPVCG4 | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827A | Samples |
| 74FCT162827BTPVCG4 | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827B | Samples |
| 74FCT162827CTPACT | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827C | Samples |
| 74FCT162827ETPACT | OBSOLETE | TSSOP | DGG | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| 74FCT162827ETPVCT | OBSOLETE | SSOP | DL | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| 74FCT16827ATPACTE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827A | Samples |
| 74FCT16827ATPACTG4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827A | Samples |
| 74FCT16827ATPVCG4 | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827A | Samples |
| 74FCT16827CTPACTE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| 74FCT16827CTPACTG4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| 74FCT16827CTPVCG4 | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| 74FCT16827CTPVCTG4 | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| CY74FCT162827ATPVC | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827A | Samples |
| CY74FCT162827BTPVC | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827B | Samples |
| CY74FCT162827ETPAC | OBSOLETE | TSSOP | DGG | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| CY74FCT162827ETPVC | OBSOLETE | SSOP | DL | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| CY74FCT16827ATPACT | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827A | Samples |
| CY74FCT16827ATPVC | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| CY74FCT16827CTPACT | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| CY74FCT16827CTPVC | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| CY74FCT16827CTPVCT | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT16827C | Samples |
| CY74FCT16827ETPAC | OBSOLETE | TSSOP | DGG | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| CY74FCT16827ETPACT | OBSOLETE | TSSOP | DGG | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| CY74FCT16827ETPVC | OBSOLETE | SSOP | DL | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| CY74FCT16827ETPVCT | OBSOLETE | SSOP | DL | 56 | | TBD | Call TI | Call TI | -40 to 85 | | |
| FCT162827ATPACTE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827A | Samples |
| FCT162827ATPACTG4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827A | Samples |
| FCT162827CTPACTE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827C | Samples |
| FCT162827CTPACTG4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | FCT162827C | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| 74FCT162827ATPACT | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| 74FCT162827CTPACT | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| CY74FCT16827ATPACT | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| CY74FCT16827CTPACT | TSSOP | DGG | 56 | 2000 | 330.0 | 24.4 | 8.6 | 15.6 | 1.8 | 12.0 | 24.0 | Q1 |
| CY74FCT16827CTPVCT | SSOP | DL | 56 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| 74FCT162827ATPACT | TSSOP | DGG | 56 | 2000 | 367.0 | 367.0 | 45.0 |
| 74FCT162827CTPACT | TSSOP | DGG | 56 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT16827ATPACT | TSSOP | DGG | 56 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT16827CTPACT | TSSOP | DGG | 56 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT16827CTPVCT | SSOP | DL | 56 | 1000 | 367.0 | 367.0 | 55.0 |

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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